

74LVC1G14

Single Schmitt-trigger inverter

Rev. 07 — 18 July 2007

Product data sheet

1. General description

The 74LVC1G14 provides the inverting buffer function with Schmitt-trigger action.

The input can be driven from either 3.3 V or 5 V devices. This feature allows the use of this device in a mixed 3.3 V and 5 V environment. Schmitt-trigger action at the input makes the circuit tolerant for slower input rise and fall time.

This device is fully specified for partial power-down applications using I_{OFF} . The I_{OFF} circuitry disables the output, preventing the damaging backflow current through the device when it is powered down.

2. Features

- Wide supply voltage range from 1.65 V to 5.5 V
- High noise immunity
- Complies with JEDEC standard:
 - ◆ JESD8-7 (1.65 V to 1.95 V)
 - ◆ JESD8-5 (2.3 V to 2.7 V)
 - ◆ JESD8-B/JESD36 (2.7 V to 3.6 V).
- ± 24 mA output drive ($V_{CC} = 3.0$ V)
- CMOS low power consumption
- Latch-up performance exceeds 250 mA
- Direct interface with TTL levels
- Unlimited rise and fall times
- Input accepts voltages up to 5 V
- Multiple package options
- ESD protection:
 - ◆ HBM JESD22-A114E exceeds 2000 V
 - ◆ MM JESD22-A115-A exceeds 200 V.
- Specified from -40 °C to $+85$ °C and -40 °C to $+125$ °C.

3. Applications

- Wave and pulse shaper
- Astable multivibrator
- Monostable multivibrator

4. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
74LVC1G14GW	−40 °C to +125 °C	TSSOP5	plastic thin shrink small outline package; 5 leads; body width 1.25 mm	SOT353-1
74LVC1G14GV	−40 °C to +125 °C	SC-74A	plastic surface-mounted package; 5 leads	SOT753
74LVC1G14GM	−40 °C to +125 °C	XSON6	plastic extremely thin small outline package; no leads; 6 terminals; body 1 × 1.45 × 0.5 mm	SOT886
74LVC1G14GF	−40 °C to +125 °C	XSON6	plastic extremely thin small outline package; no leads; 6 terminals; body 1 × 1 × 0.5 mm	SOT891

5. Marking

Table 2. Marking

Type number	Marking code
74LVC1G14GW	VF
74LVC1G14GV	V14
74LVC1G14GM	VF
74LVC1G14GF	VF

6. Functional diagram

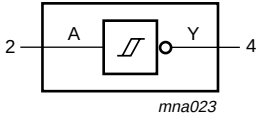


Fig 1. Logic symbol

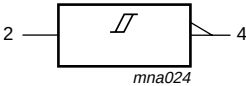


Fig 2. IEC logic symbol

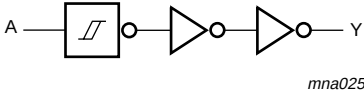


Fig 3. Logic diagram

7. Pinning information

7.1 Pinning

74LVC1G14

001aab655

Pin 1: n.c., Pin 2: A, Pin 3: GND, Pin 4: Y, Pin 5: V_{CC}

74LVC1G14

001aab656

Transparent top view

Pin 1: n.c., Pin 2: A, Pin 3: GND, Pin 4: Y, Pin 5: n.c., Pin 6: V_{CC}

74LVC1G14

001aae976

Transparent top view

Pin 1: n.c., Pin 2: A, Pin 3: GND, Pin 4: Y, Pin 5: n.c., Pin 6: V_{CC}

Fig 4. Pin configuration SOT353-1 and SOT753

Fig 5. Pin configuration SOT886

Fig 6. Pin configuration SOT891

7.2 Pin description

Table 3. Pin description

Symbol	Pin		Description
	SOT353-1/SOT753	SOT886/SOT891	
n.c.	1	1	not connected
A	2	2	data input
GND	3	3	ground (0 V)
Y	4	4	data output
n.c.	-	5	not connected
V _{CC}	5	6	supply voltage

8. Functional description

Table 4. Function table^[1]

Input	Output
A	Y
L	H
H	L

[1] H = HIGH voltage level; L = LOW voltage level

9. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CC}	supply voltage		-0.5	+6.5	V
V_I	input voltage		[1] -0.5	+6.5	V
V_O	output voltage	Active mode	[1][2] -0.5	$V_{CC} + 0.5$	V
		Power-down mode	[1][2] -0.5	+6.5	V
I_{IK}	input clamping current	$V_I < 0$ V	-50	-	mA
I_{OK}	output clamping current	$V_O > V_{CC}$ or $V_O < 0$ V	-	± 50	mA
I_O	output current	$V_O = 0$ V to V_{CC}	-	± 50	mA
I_{CC}	supply current		-	+100	mA
I_{GND}	ground current		-100	-	mA
T_{stg}	storage temperature		-65	+150	°C
P_{tot}	total power dissipation	$T_{amb} = -40$ °C to +125 °C	[3] -	250	mW

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] When $V_{CC} = 0$ V (Power-down mode), the output voltage can be 5.5 V in normal operation.

[3] For TSSOP5 and SC-74A packages: above 87.5 °C the value of P_{tot} derates linearly with 4.0 mW/K.

For XSON6 packages: above 45 °C the value of P_{tot} derates linearly with 2.4 mW/K.

10. Recommended operating conditions

Table 6. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{CC}	supply voltage		1.65	-	5.5	V
V_I	input voltage		0	-	5.5	V
V_O	output voltage	Active mode	0	-	V_{CC}	V
		Power-down mode; $V_{CC} = 0$ V	0	-	5.5	V
T_{amb}	ambient temperature		-40	-	+125	°C

11. Static characteristics

Table 7. Static characteristics

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	–40 °C to +85 °C			–40 °C to +125 °C		Unit
			Min	Typ ^[1]	Max	Min	Max	
V _{OH}	HIGH-level output voltage	V _I = V _{IH} or V _{IL}						
		I _O = –100 µA; V _{CC} = 1.65 V to 5.5 V	V _{CC} – 0.1	-	-	V _{CC} – 0.1	-	V
		I _O = –4 mA; V _{CC} = 1.65 V	1.2	1.54	-	0.95	-	V
		I _O = –8 mA; V _{CC} = 2.3 V	1.9	2.15	-	1.7	-	V
		I _O = –12 mA; V _{CC} = 2.7 V	2.2	2.50	-	1.9	-	V
		I _O = –24 mA; V _{CC} = 3.0 V	2.3	2.62	-	2.0	-	V
V _{OL}	LOW-level output voltage	V _I = V _{IH} or V _{IL}						
		I _O = 100 µA; V _{CC} = 1.65 V to 5.5 V	-	-	0.10	-	0.10	V
		I _O = 4 mA; V _{CC} = 1.65 V	-	0.07	0.45	-	0.70	V
		I _O = 8 mA; V _{CC} = 2.3 V	-	0.12	0.30	-	0.45	V
		I _O = 12 mA; V _{CC} = 2.7 V	-	0.17	0.40	-	0.60	V
		I _O = 24 mA; V _{CC} = 3.0 V	-	0.33	0.55	-	0.80	V
I _I	input leakage current	V _I = 5.5 V or GND; V _{CC} = 0 V to 5.5 V	-	±0.1	±5	-	±100	µA
		V _I or V _O = 5.5 V; V _{CC} = 0 V	-	±0.1	±10	-	±200	µA
I _{CC}	supply current	V _I = 5.5 V or GND; I _O = 0 A; V _{CC} = 1.65 V to 5.5 V	-	0.1	10	-	200	µA
ΔI _{CC}	additional supply current	V _I = V _{CC} – 0.6 V; I _O = 0 A; V _{CC} = 2.3 V to 5.5 V	-	5	500	-	5000	µA
C _I	input capacitance	V _{CC} = 3.3 V; V _I = GND to V _{CC}	-	5.0	-	-	-	pF

[1] All typical values are measured at maximum V_{CC} and T_{amb} = 25 °C.

Table 8. Transfer characteristics

Voltages are referenced to GND (ground = 0 V); for load circuit see [Figure 8](#).

Symbol	Parameter	Conditions	–40 °C to +85 °C			–40 °C to +125 °C		Unit
			Min	Typ ^[1]	Max	Min	Max	
V _{T+}	positive-going threshold voltage	see Figure 9 and Figure 10						
		V _{CC} = 1.8 V	0.82	1.0	1.14	0.79	1.14	V
		V _{CC} = 2.3 V	1.03	1.2	1.40	1.00	1.40	V
		V _{CC} = 3.0 V	1.29	1.5	1.71	1.26	1.71	V
		V _{CC} = 4.5 V	1.84	2.1	2.36	1.81	2.36	V
		V _{CC} = 5.5 V	2.19	2.5	2.79	2.16	2.79	V

Table 8. Transfer characteristics ...continued

Voltages are referenced to GND (ground = 0 V); for load circuit see [Figure 8](#).

Symbol	Parameter	Conditions	–40 °C to +85 °C			–40 °C to +125 °C		Unit
			Min	Typ ^[1]	Max	Min	Max	
V _{T–}	negative-going threshold voltage	see Figure 9 and Figure 10						
		V _{CC} = 1.8 V	0.46	0.6	0.75	0.46	0.78	V
		V _{CC} = 2.3 V	0.65	0.8	0.96	0.65	0.99	V
		V _{CC} = 3.0 V	0.88	1.0	1.24	0.88	1.27	V
		V _{CC} = 4.5 V	1.32	1.5	1.84	1.32	1.87	V
		V _{CC} = 5.5 V	1.58	1.8	2.24	1.58	2.27	V
V _H	hysteresis voltage	(V _{T+} – V _{T–}); see Figure 9 , Figure 10 and Figure 11						
		V _{CC} = 1.8 V	0.26	0.4	0.51	0.19	0.51	V
		V _{CC} = 2.3 V	0.28	0.4	0.57	0.22	0.57	V
		V _{CC} = 3.0 V	0.31	0.5	0.64	0.25	0.64	V
		V _{CC} = 4.5 V	0.40	0.6	0.77	0.34	0.77	V
		V _{CC} = 5.5 V	0.47	0.6	0.88	0.41	0.88	V

[1] All typical values are measured at T_{amb} = 25 °C

12. Dynamic characteristics

Table 9. Dynamic characteristics

Voltages are referenced to GND (ground = 0 V); for load circuit see [Figure 8](#).

Symbol	Parameter	Conditions	–40 °C to +85 °C			–40 °C to +125 °C		Unit
			Min	Typ ^[1]	Max	Min	Max	
t _{pd}	propagation delay	A to Y; see Figure 7 ^[2]						
		V _{CC} = 1.65 V to 1.95 V	1.0	4.1	11.0	1.0	14.0	ns
		V _{CC} = 2.3 V to 2.7 V	0.7	2.8	6.5	0.7	8.5	ns
		V _{CC} = 2.7 V	0.7	3.2	6.5	0.7	8.5	ns
		V _{CC} = 3.0 V to 3.6 V	0.7	3.0	5.5	0.7	7.0	ns
		V _{CC} = 4.5 V to 5.5 V	0.7	2.2	5.0	0.7	6.5	ns
C _{PD}	power dissipation capacitance	V _{CC} = 3.3 V; V _I = GND to V _{CC} ^[3]	-	15.4	-	-	-	pF

[1] Typical values are measured at T_{amb} = 25 °C and V_{CC} = 1.8 V, 2.5 V, 2.7 V, 3.3 V and 5.0 V respectively.

[2] t_{pd} is the same as t_{PLH} and t_{PHL}.

[3] C_{PD} is used to determine the dynamic power dissipation (P_D in μW).

$$P_D = C_{PD} \times V_{CC}^2 \times f_i + (C_L \times V_{CC}^2 \times f_o) \text{ where:}$$

f_i = input frequency in MHz;

f_o = output frequency in MHz;

C_L = output load capacitance in pF;

V_{CC} = supply voltage in V.

13. Waveforms

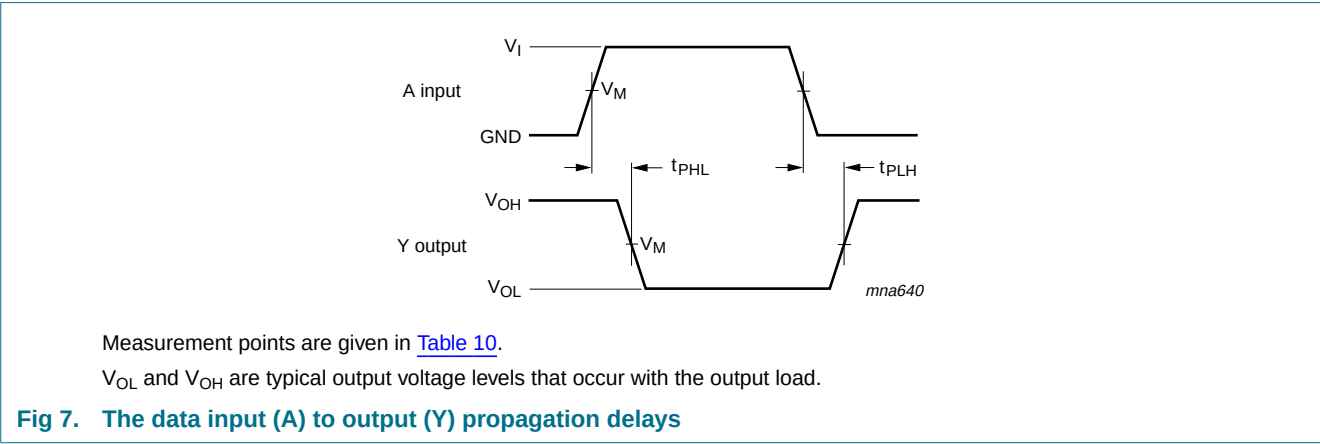


Table 10. Measurement points

Supply voltage	Input	Output
V_{CC}	V_M	V_M
1.65 V to 1.95 V	$0.5V_{CC}$	$0.5V_{CC}$
2.3 V to 2.7 V	$0.5V_{CC}$	$0.5V_{CC}$
2.7 V	1.5 V	1.5 V
3.0 V to 3.6 V	1.5 V	1.5 V
4.5 V to 5.5 V	$0.5V_{CC}$	$0.5V_{CC}$

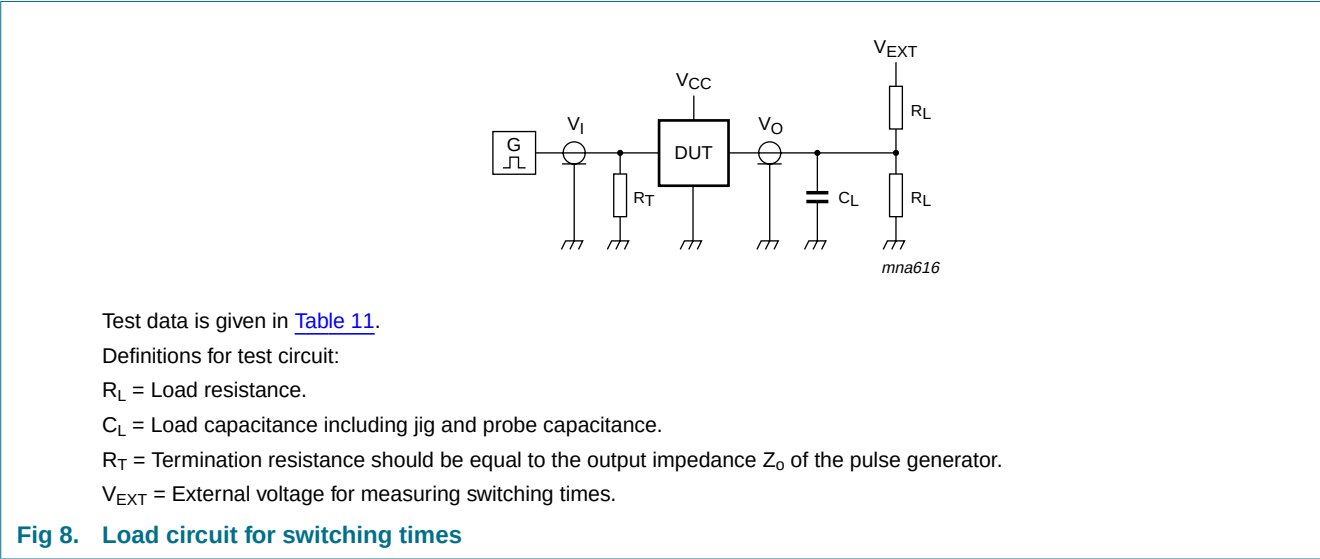
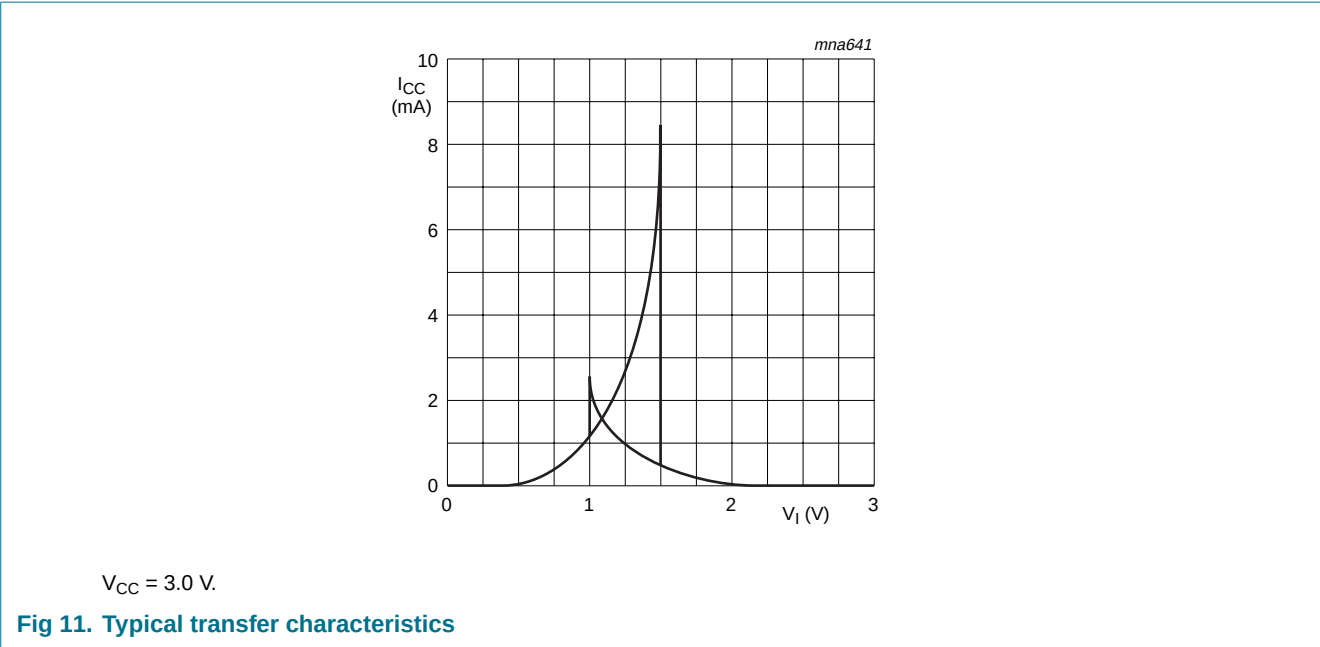
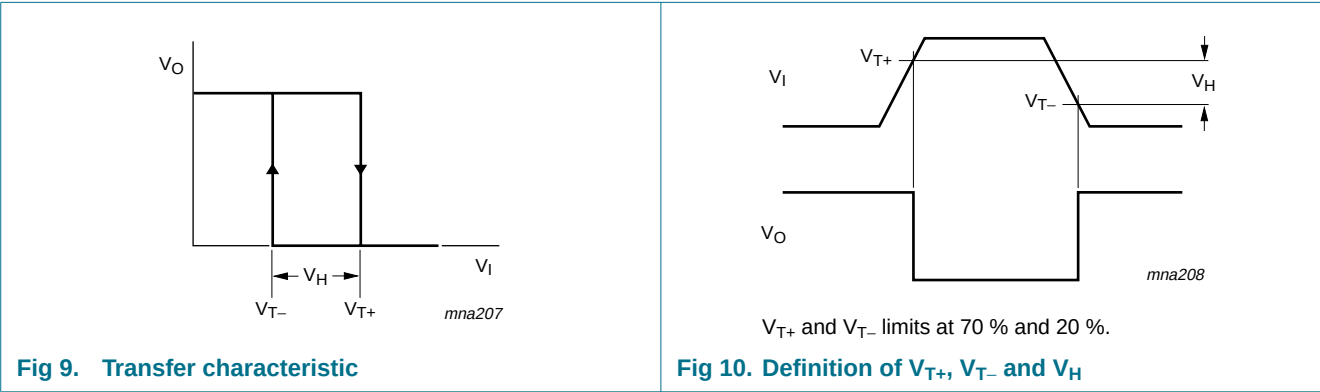


Table 11. Test data

Supply voltage	Input		Load		V _{EXT}
V _{CC}	V _I	t _r = t _f	C _L	R _L	t _{PLH} , t _{PHL}
1.65 V to 1.95 V	V _{CC}	≤ 2.0 ns	30 pF	1 kΩ	open
2.3 V to 2.7 V	V _{CC}	≤ 2.0 ns	30 pF	500 Ω	open
2.7 V	2.7 V	≤ 2.5 ns	50 pF	500 Ω	open
3.0 V to 3.6 V	2.7 V	≤ 2.5 ns	50 pF	500 Ω	open
4.5 V to 5.5 V	V _{CC}	≤ 2.5 ns	50 pF	500 Ω	open

14. Waveforms transfer characteristics



15. Application information

The slow input rise and fall times cause additional power dissipation, this can be calculated using the following formula:

$$P_{\text{add}} = f_i \times (t_r \times \Delta I_{\text{CC(AV)}} + t_f \times \Delta I_{\text{CC(AV)}}) \times V_{\text{CC}} \text{ where:}$$

P_{add} = additional power dissipation (μW);

f_i = input frequency (MHz);

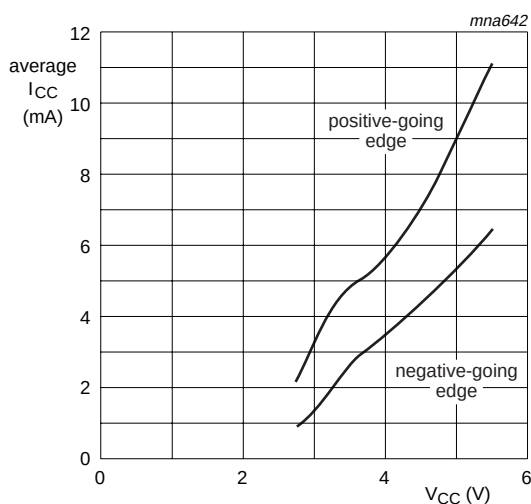
t_r = input rise time (ns); 10 % to 90 %;

t_f = input fall time (ns); 90 % to 10 %;

$\Delta I_{\text{CC(AV)}}$ = average additional supply current (μA).

Average $\Delta I_{\text{CC(AV)}}$ differs with positive or negative input transitions, as shown in [Figure 12](#).

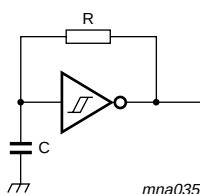
An example of a relaxation circuit using the 74LVC1G14 is shown in [Figure 13](#).



Linear change of V_I between 0.8 V to 2.0 V.

All values given are typical unless otherwise specified.

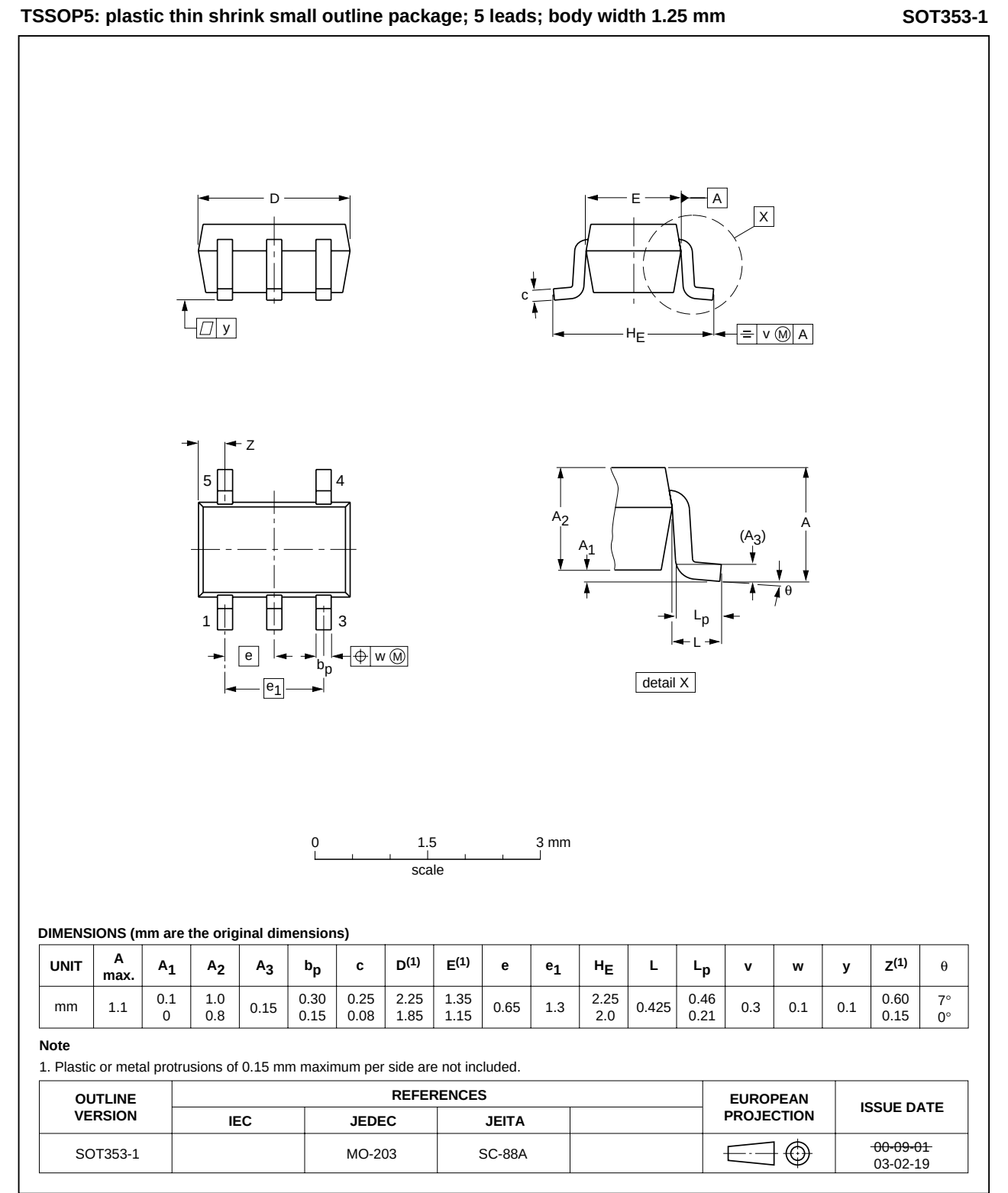
Fig 12. Average additional supply current as a function of supply voltage



$$f = \frac{1}{T} \approx \frac{1}{0.5 \times RC}$$

Fig 13. Relaxation oscillator

16. Package outline



Plastic surface-mounted package; 5 leads

SOT753

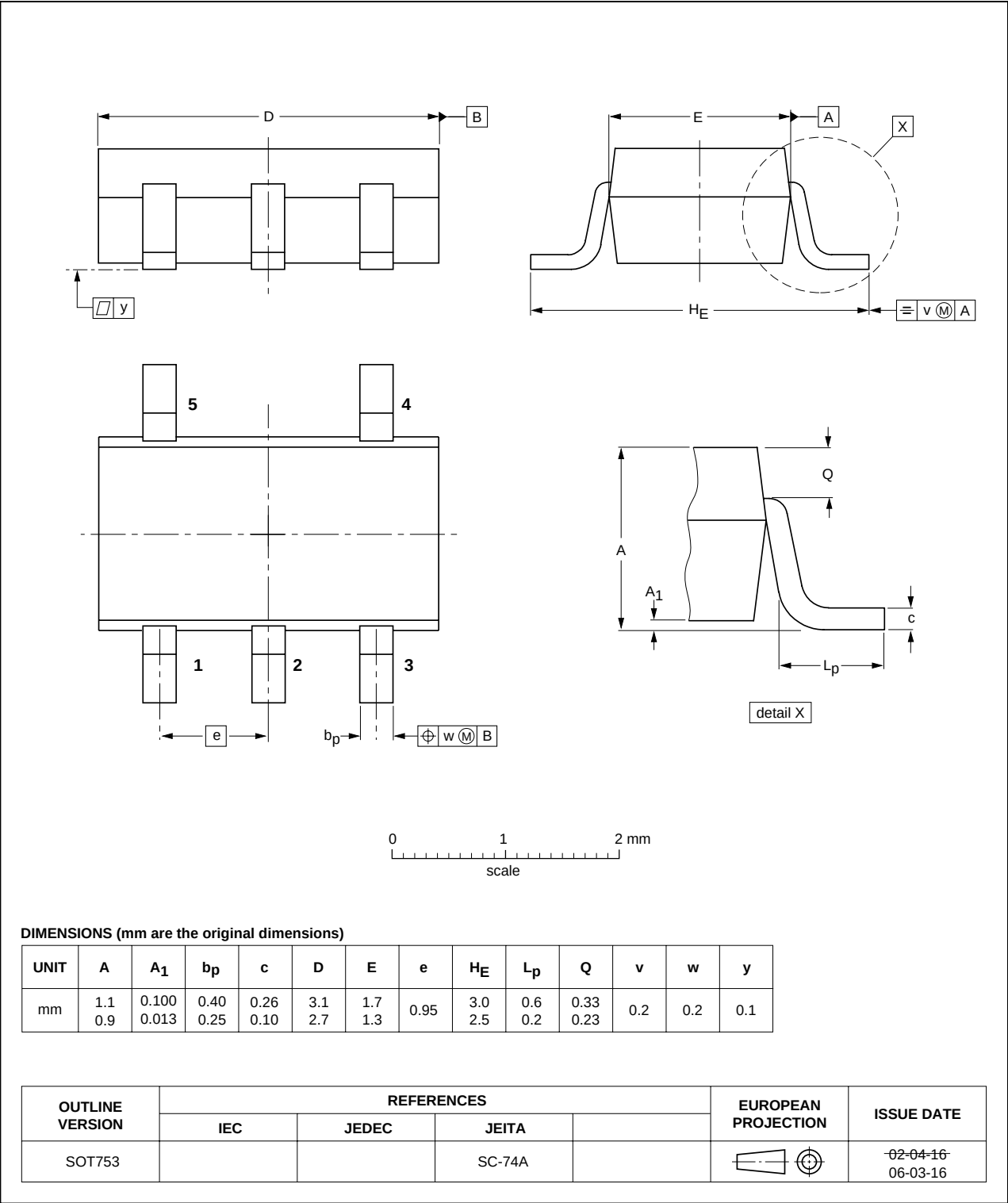


Fig 15. Package outline SOT753 (SC-74A)

XSON6: plastic extremely thin small outline package; no leads; 6 terminals; body 1 x 1.45 x 0.5 mm

SOT886

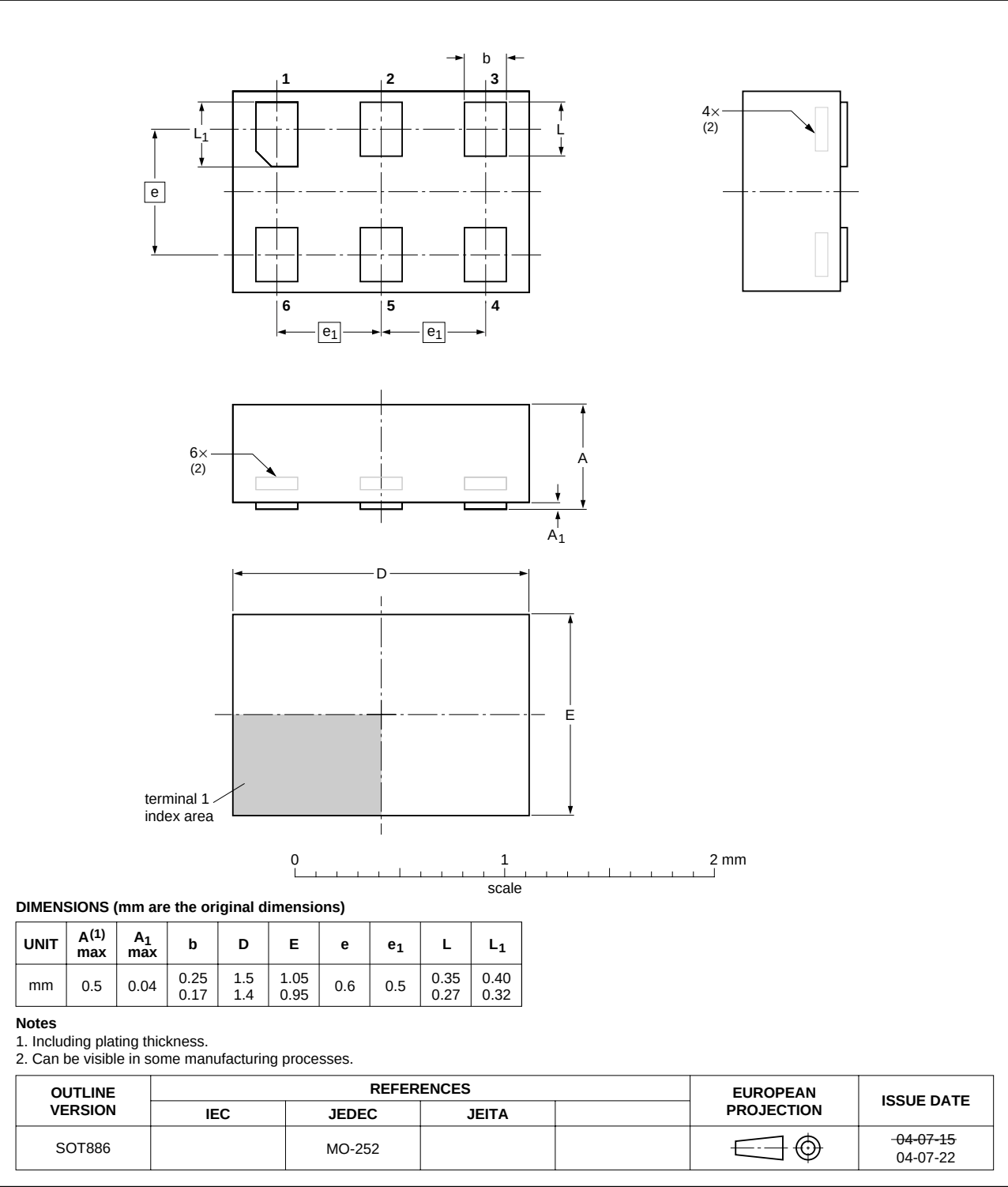


Fig 16. Package outline SOT886 (XSON6)

XSON6: plastic extremely thin small outline package; no leads; 6 terminals; body 1 x 1 x 0.5 mm

SOT891

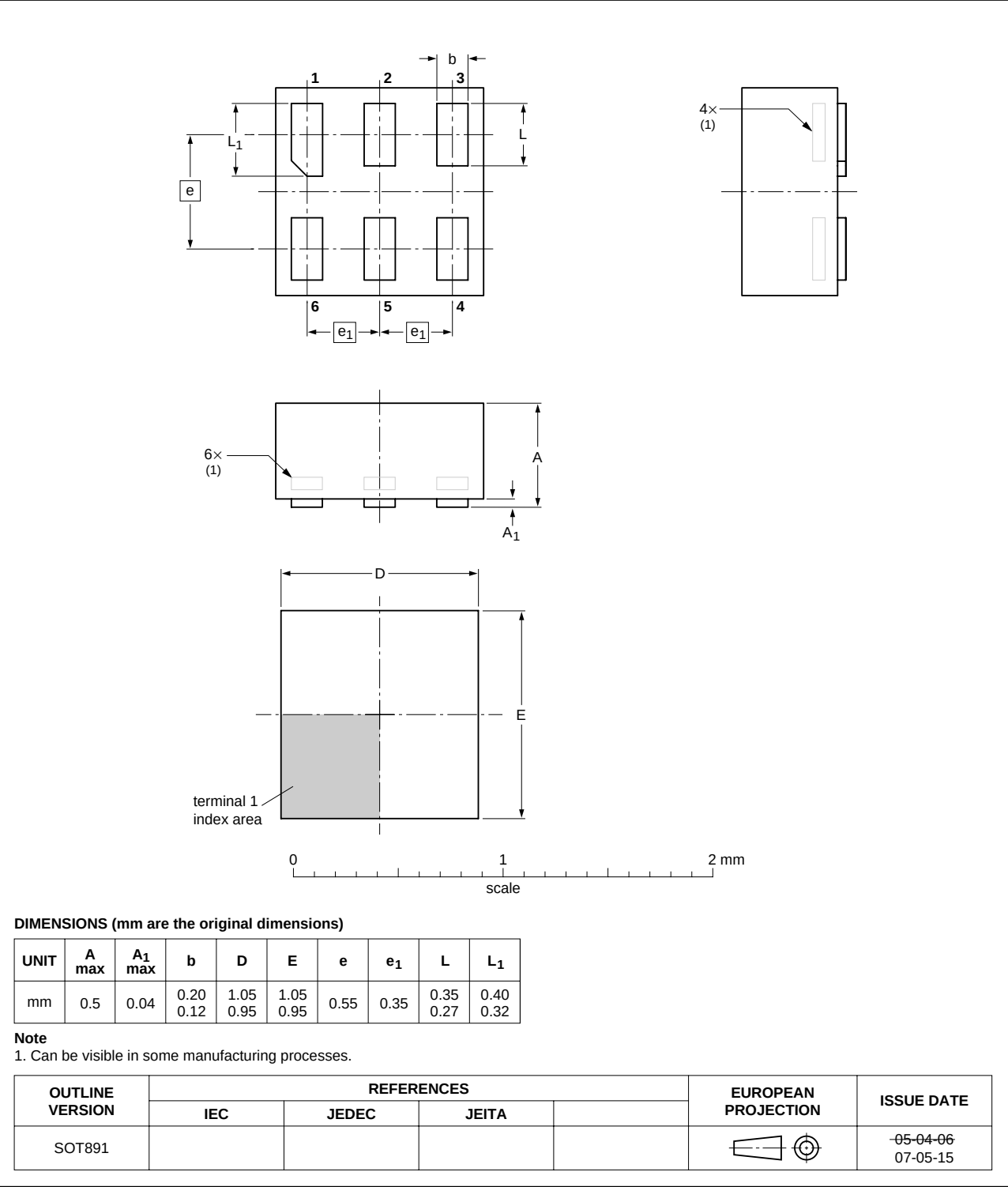


Fig 17. Package outline SOT891 (XSON6)

17. Abbreviations

Table 12. Abbreviations

Acronym	Description
CMOS	Complementary Metal Oxide Semiconductor
TTL	Transistor-Transistor Logic
HBM	Human Body Model
ESD	ElectroStatic Discharge
MM	Machine Model
DUT	Device Under Test

18. Revision history

Table 13. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74LVC1G14_7	20070718	Product data sheet	-	74LVC1G14_6
Modifications:	• The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors. • Legal texts have been adapted to the new company name where appropriate. • Section 11 “Static characteristics”: Changed: Conditions for input leakage current and supply current. • New package outline drawing for XSON6/SOT891.			
74LVC1G14_6	20060615	Product data sheet	-	74LVC1G14_5
74LVC1G14_5	20040910	Product specification	-	74LVC1G14_4
74LVC1G14_4	20021119	Product specification	-	74LVC1G14_3
74LVC1G14_3	20020521	Product specification	-	74LVC1G14_2
74LVC1G14_2	20010406	Product specification	-	74LVC1G14_1
74LVC1G14_1	20001212	Product specification	-	-

19. Legal information

19.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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